

# Kazuhiro Ito

## List of Publications by Year in descending order

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62  
papers

532  
citations

759233

12  
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677142

22  
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62  
docs citations

62  
times ranked

425  
citing authors

#	ARTICLE	IF	CITATIONS
1	Fatigue strength improvement due to alloying steel weld toes with WC tool constituent elements through friction stir processing. <i>International Journal of Advanced Manufacturing Technology</i> , 2022, 119, 6203-6213.	3.0	0
2	Characterization of Shock Wave Damages in Explosion Welded Mo/Cu Clads. <i>Metals</i> , 2021, 11, 501.	2.3	2
3	Evaluation of Hydrogen-induced Cracking Behavior in Duplex Stainless Steel by Numerical Simulation of Stress and Diffusible Hydrogen Distribution at the Microstructural Scale. <i>ISIJ International</i> , 2021, 61, 1135-1142.	1.4	2
4	Numerical Simulation on Effect of Microstructure on Hydrogen-induced Cracking Behavior in Duplex Stainless Steel Weld Metal. <i>ISIJ International</i> , 2021, 61, 1236-1244.	1.4	2
5	Study on Effect of Microstructure on Hydrogen Cracking in Duplex Stainless Steel Welds. <i>The Proceedings of the Materials and Mechanics Conference</i> , 2021, 2021, OS1601.	0.0	0
6	Cladding of a crack-free W plate on Cu plates using explosive welding at higher collision velocity with lower collision angle. <i>Results in Materials</i> , 2020, 5, 100023.	1.8	5
7	Evaluation of Hydrogen-induced Cracking Behavior in Duplex Stainless Steel by Numerical Simulation of Stress and Diffusible Hydrogen Distribution at the Microstructural Scale. <i>Tetsu-To-Hagane/Journal of the Iron and Steel Institute of Japan</i> , 2020, 106, 214-223.	0.4	2
8	Numerical Simulation on Effect of Microstructure on Hydrogen-induced Cracking Behavior in Duplex Stainless Steel Weld Metal. <i>Tetsu-To-Hagane/Journal of the Iron and Steel Institute of Japan</i> , 2020, 106, 224-234.	0.4	1
9	Visualizing the vibration effect on the tandem-pulsed gas metal arc welding in the presence of surface tension active elements. <i>International Journal of Heat and Mass Transfer</i> , 2020, 161, 120310.	4.8	14
10	Predicting Tensile Properties of Friction-Stir-Welded 6063 Aluminum with Experimentally Measured Welding Heat Input. <i>Acta Metallurgica Sinica (English Letters)</i> , 2020, 33, 1235-1242.	2.9	3
11	Metallurgical Characterization of Penetration Shape Change in Workpiece Vibration-Assisted Tandem-Pulsed Gas Metal Arc Welding. <i>Materials</i> , 2020, 13, 3096.	2.9	10
12	A unique CEL numerical method on material flow in a molten pool of workpiece vibration assisted welding. <i>Yosetsu Gakkai Ronbunshu/Quarterly Journal of the Japan Welding Society</i> , 2020, 38, 54s-58s.	0.5	2
13	Surface Microstructure Modifications of Low Carbon Steel Welds Produced by Low-Heat-Input Friction Stir Processing. <i>Materials Transactions</i> , 2020, 61, 1613-1619.	1.2	4
14	Friction stir welding of ultra high-purity aluminium thin sheets never to lower high conductivity at ultra-low temperature. <i>Welding International</i> , 2020, 34, 125-137.	0.7	1
15	Microstructure and Impact Toughness Relationship for Different Nickel Level of Electrode in Multi-pass FCA Welded SM570-TMC Steel Joint. <i>Yosetsu Gakkai Ronbunshu/Quarterly Journal of the Japan Welding Society</i> , 2020, 38, 154s-158s.	0.5	1
16	Study on Residual Stress by Neutron Diffraction in SM570-TMC Welded by Flux-Cored Wires Containing Different Nickel. <i>Yosetsu Gakkai Ronbunshu/Quarterly Journal of the Japan Welding Society</i> , 2020, 38, 116s-120s.	0.5	0
17	Friction stir welding of ultrahigh-purity aluminum thin sheets never to lower high conductivity at ultra-low temperature. <i>Yosetsu Gakkai Ronbunshu/Quarterly Journal of the Japan Welding Society</i> , 2020, 38, 253-262.	0.5	0
18	Benefits of intermediate-layer formation at the interface of Nb/Cu and Ta/Cu explosive clads. <i>Materials and Design</i> , 2019, 166, 107610.	7.0	48

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19	TEM Characterization of Explosive Cladding Interfaces between Refractory Metal (group V or VI) and Cu Plates. Journal of Smart Processing, 2019, 8, 261-266.	0.1	0
20	Effects of Microstructural Modification by Friction Stir Processing on Fracture Toughness of Low-carbon Steel Welds. Journal of Smart Processing, 2019, 8, 29-35.	0.1	1
21	Effects of Insert Metal Type on Interfacial Microstructure During Dissimilar Joining of TiAl Alloy to SCM440 by Friction Welding. Metals and Materials International, 2018, 24, 626-632.	3.4	5
22	Effects of heat-affected-zone microstructure and molten-zinc temperature on zinc embrittlement cracking induced. Yosetsu Gakkai Ronbunshu/Quarterly Journal of the Japan Welding Society, 2018, 36, 230-237.	0.5	0
23	Application of Friction Stir Processing to Weld Toe for Fatigue Strength Improvement of High-Strength Low-Alloy Steel Joint. Yosetsu Gakkai Ronbunshu/Quarterly Journal of the Japan Welding Society, 2018, 36, 1WL-4WL.	0.5	3
24	Study on the Microstructure and Liquid Phase Formation in a Semisolid Gray Cast Iron. Metallurgical and Materials Transactions B: Process Metallurgy and Materials Processing Science, 2017, 48, 2293-2303.	2.1	3
25	Dissimilar materials joining between stainless steel and carbon fiber reinforced thermoplastic by friction lap joining. Yosetsu Gakkai Ronbunshu/Quarterly Journal of the Japan Welding Society, 2017, 35, 29-35.	0.5	11
26	Report of Visual-JW 2016. Yosetsu Gakkai Shi/Journal of the Japan Welding Society, 2017, 86, 189-191.	0.1	0
27	Phase transitions from semiconductive amorphous to conductive polycrystalline in indium silicon oxide thin films. Applied Physics Letters, 2016, 109, .	3.3	13
28	Low-Temperature Synthesis of High-Adhesion Cu(Mg) Alloy Films on Glass Substrates. Journal of Electronic Materials, 2014, 43, 2540-2547.	2.2	5
29	Growth of Ti-Based Interface Layer in Cu(Ti)/Glass Samples. Materials Transactions, 2011, 52, 491-497.	1.2	2
30	OS15-1-1 Damage Evaluation and Life Assessment of Heat-Resisting Steels and Alloys by Using Positron Annihilation. The Abstracts of ATEM International Conference on Advanced Technology in Experimental Mechanics Asian Conference on Experimental Mechanics, 2011, 2011.10, _OS15-1-1.	0.0	0
31	Resistivity Reduction and Adhesion Increase Induced by Surface and Interface Segregation of Ti Atoms in Cu(Ti) Alloy Films on Glass Substrates. Materials Transactions, 2010, 51, 1627-1632.	1.2	8
32	Ti-Rich Barrier Layers Self-Formed on Porous Low-k Layers Using Cu(1Åat.%ÅTi) Alloy Films. Journal of Electronic Materials, 2010, 39, 1326-1333.	2.2	6
33	Characterization of self-formed Ti-based barrier layers in Cu(Ti)/dielectric-layer samples using X-ray Photoelectron Spectroscopy. , 2010, , .		1
34	Self-Formed Ti-Rich Barrier Layers in Cu(Ti)•Low-k Samples. , 2009, , .		0
35	Ohmic contacts on silicon carbide: The first monolayer and its electronic effect. Physical Review B, 2009, 80, .	3.2	63
36	Rutherford Backscattering Spectrometry Analysis of Growth Rate and Activation Energy for Self-formed Ti-rich Interface Layers in Cu(Ti)/Low-k Samples. Materials Research Society Symposia Proceedings, 2009, 1156, 1.	0.1	0

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37	Effects of TiN Buffer Layer Thickness on GaN Growth. Journal of Electronic Materials, 2009, 38, 511-517.	2.2	4
38	Rutherford Backscattering Spectrometry Analysis of Self-Formed Ti-Rich Interface Layer Growth in Cu(Ti)/Low-k Samples. Journal of Electronic Materials, 2009, 38, 1913-1920.	2.2	17
39	Growth analysis of self-formed Ti-rich interface layers in Cu(Ti)/dielectric-layer samples using Rutherford Backscattering Spectrometry. , 2009, , .		0
40	Growth and Microstructure of Epitaxial Ti<sub>3</sub>SiC<sub>2</sub> Contact Layers on SiC. Materials Transactions, 2009, 50, 1071-1075.	1.2	30
41	Characterization of Self-Formed Ti-Rich Interface Layers in Cu(Ti)/Low-k Samples. Journal of Electronic Materials, 2008, 37, 1148-1157.	2.2	29
42	Simultaneous Formation of Ni/Al Ohmic Contacts to Both n- and p-Type 4H-SiC. Journal of Electronic Materials, 2008, 37, 1674-1680.	2.2	21
43	Simultaneous Formation of n- and p-Type Ohmic Contacts to 4H-SiC Using the Binary Ni/Al System. Materials Research Society Symposia Proceedings, 2008, 1069, 1.	0.1	0
44	Self-formation of Ti-rich Layers at Cu(Ti)/low-k Interfaces. Materials Research Society Symposia Proceedings, 2008, 1079, 1.	0.1	0
45	Effects of Dielectric-Layer Composition on Growth of Self-Formed Ti-Rich Barrier Layers in Cu(1) Tj ETQq1 1 0.784314 rgBT /Overlock	1.2	5
46	Effects of Al ion implantation to 4H-SiC on the specific contact resistance of TiAl-based contact materials. Science and Technology of Advanced Materials, 2006, 7, 496-501.	6.1	18
47	Epitaxial growth of GaN layers on metallic TiN buffer layers. Journal of Electronic Materials, 2006, 35, 1806-1811.	2.2	12
48	Epitaxial GaN Layer Growth Using Nitrogen Enriched TiN Buffer Layers. Materials Research Society Symposia Proceedings, 2006, 916, 6.	0.1	1
49	Simultaneous Formation of Ohmic Contacts for Both N- and P-Type 4H-Sic Using Nial-Based Contact Materials. Materials Research Society Symposia Proceedings, 2006, 911, 5.	0.1	1
50	Grain Growth Mechanism of Cu Thin Films. Materials Transactions, 2005, 46, 1737-1740.	1.2	13
51	Growth of GaN on Nitriding TiN Buffer Layers. Materials Transactions, 2005, 46, 1975-1978.	1.2	9
52	The effect of Nb and W alloying additions to the thermal expansion anisotropy and elastic properties of Mo5Si3. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2005, 36, 533-538.	2.2	12
53	Oxidation protective silicide coating on Mo-Si-B alloys. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2005, 36, 627-636.	2.2	25
54	Formation of Ti diffusion barrier layers in Thin Cu(Ti) alloy films. Journal of Electronic Materials, 2005, 34, 592-599.	2.2	78

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55	Simultaneous formation of p- and n-type ohmic contacts to 4H-SiC using the ternary Ni/Ti/Al system. Journal of Electronic Materials, 2005, 34, 1310-1312.	2.2	35
56	Interfacial Microstructures of TiAl-Based Ohmic Contacts to p-Type SiC Semiconductor. Materia Japan, 2004, 43, 992-992.	0.1	0
57	Low Thermal Conductivity and Related Thermoelectric Properties of Zn <sub>4</sub> Sb <sub>3</sub> and CoSb <sub>3</sub> Thin Films. Materials Research Society Symposia Proceedings, 2003, 793, 188.	0.1	2
58	Physical and Mechanical Properties of Mo <sub>5</sub> X <sub>3</sub> +1± (X=Si, B, C) Single Crystals. Materials Research Society Symposia Proceedings, 2002, 753, 1.	0.1	0
59	On Mo-9Si-18B Alloys with T2-Moss eutectic microstructure: Mechanical Properties and Protective Silicide Coating. Materials Research Society Symposia Proceedings, 2002, 753, 1.	0.1	0
60	Reversible Hydrogen Absorption/Desorption and Related Lattice Deformation of Ti <sub>3</sub> Al Based Alloys in the Ti-Al-Nb System. Materials Research Society Symposia Proceedings, 2002, 753, 1.	0.1	0
61	Plastic deformation of single crystals with the C11b structure : Effect of the c/a axial ratio. Materials Research Society Symposia Proceedings, 2000, 646, 62.	0.1	1
62	Microstructure features and formation mechanism in a newly developed electroslag welding. Welding in the World, Le Soudage Dans Le Monde, 0, , 1.	2.5	1